Unitrode Products
from Texas Instruments

application INFO available

UCC1800/1/2/3/4/5
UCC2800/1/2/3/4/5
UCC3800/1/2/3/4/5

Low-Power BiCMOS Current-Mode PWM

FEATURES

- 100μA Typical Starting Supply Current
- 500μA Typical Operating Supply Current
- Operation to 1MHz
- Internal Soft Start
- Internal Fault Soft Start
- Internal Leading-Edge Blanking of the Current Sense Signal
- 1 Amp Totem-Pole Output
- 70ns Typical Response from Current-Sense to Gate Drive Output
- 1.5% Tolerance Voltage Reference
- Same Pinout as UC3842 and UC3842A

DESCRIPTION

The UCC1800/1/2/3/4/5 family of high-speed, low-power integrated circuits contain all of the control and drive components required for off-line and DC-to-DC fixed frequency current-mode switching power supplies with minimal parts count.

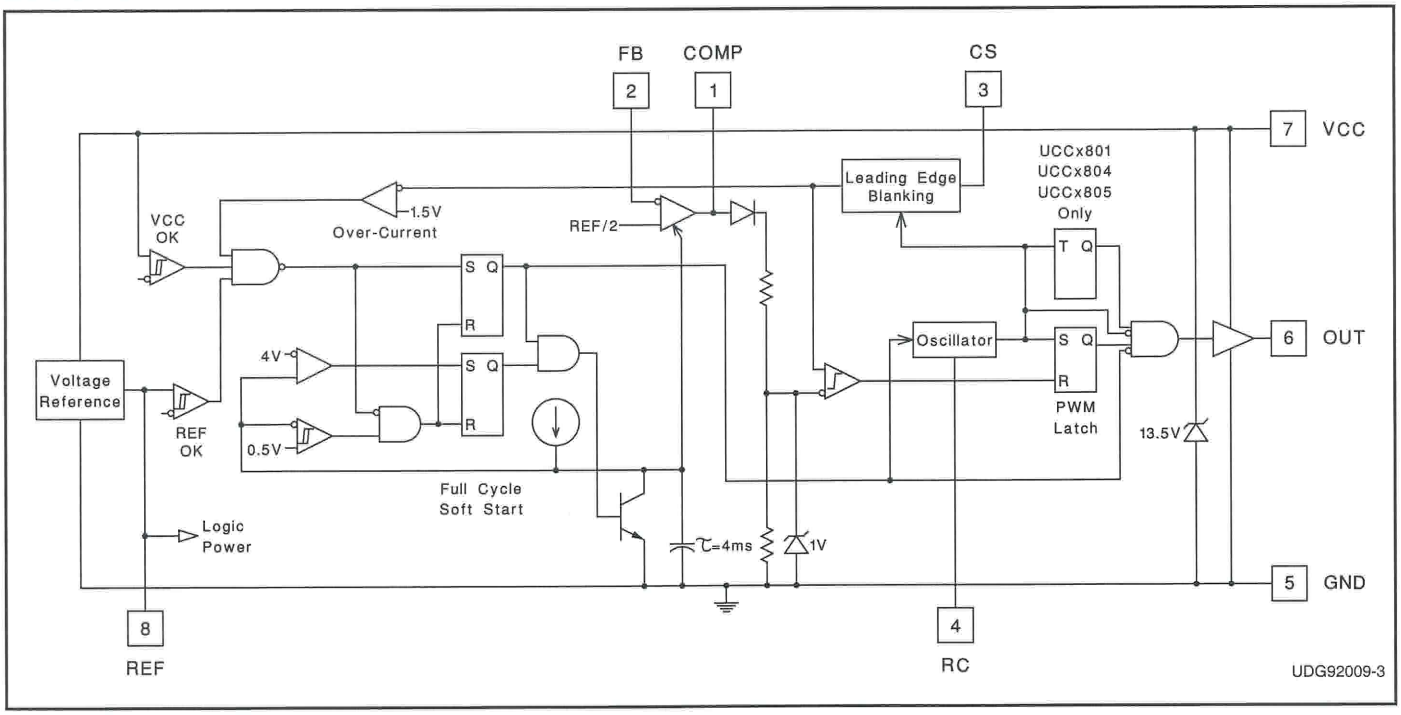
These devices have the same pin configuration as the UC1842/3/4/5 family, and also offer the added features of internal full-cycle soft start and internal leading-edge blanking of the current-sense input.

The UCC1800/1/2/3/4/5 family offers a variety of package options, temperature range options, choice of maximum duty cycle, and choice of critical voltage levels. Lower reference parts such as the UCC1803 and UCC1805 fit best into battery operated systems, while the higher reference and the higher UVLO hysteresis of the UCC1802 and UCC1804 make these ideal choices for use in off-line power supplies.

The UCC180x series is specified for operation from –55°C to +125°C, the UCC280x series is specified for operation from –40°C to +85°C, and the UCC380x series is specified for operation from 0°C to +70°C.

Part Number	Maximum Duty Cycle	Reference Voltage	Turn-On Threshold	Turn-Off Threshold
UCCx800	100%	5V	7.2V	6.9V
UCCx801	50%	5V	9.4V	7.4V
UCCx802	100%	5V	12.5V	8.3V
UCCx803	100%	4V	4.1V	3.6V
UCCx804	50%	5V	12.5V	8.3V
UCCx805	50%	4V	4.1V	3.6V

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS (Note 1)

V_{CC} Voltage (Note 2) 12.0V
V_{CC} Current (Note 2) 30.0mA
OUT Current . . . . . ±1.0A
OUT Energy (Capacitive Load) 20.0µJ
Analog Inputs (FB, CS, RC, COMP) . . . . . .
. . . . . –0.3V to the lesser of 6.3V or VCC + 0.3
Power Dissipation at T_A < +25°C (N or J Package) 1.0W
Power Dissipation at T_A < +25°C (D Package) 0.65W
Power Dissipation at T_A < +25°C (L Package) 1.375W
Storage Temperature Range . . . . . –65°C to +150°C
Lead Temperature (Soldering, 10 Seconds) . . . . . +300°C

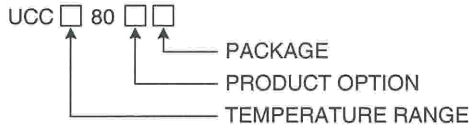
Note 1: Values beyond which damage may occur. All voltages are with respect to GND. All currents are positive into the specified terminal. Consult Unitrode databook for information regarding thermal specifications and limitations of packages.

Note 2: In normal operation V_{CC} is powered through a current limiting resistor. Absolute maximum of 12V applies when V_{CC} is driven from a low impedance source such that I_{CC} does not exceed 30mA (which includes gate drive current requirement). The resistor should be sized so that the V_{CC} voltage, under operating conditions is below 12V but above the turn off threshold.

TEMPERATURE AND PACKAGE SELECTION

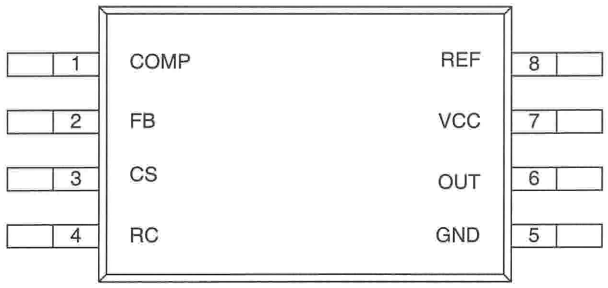
	Temperature Range	Available Packages
UCC180X	–55°C to +125°C	J, L
UCC280X	–40°C to +85°C	N, D, PW
UCC380X	0°C to +70°C	N, D, PW

ORDERING INFORMATION

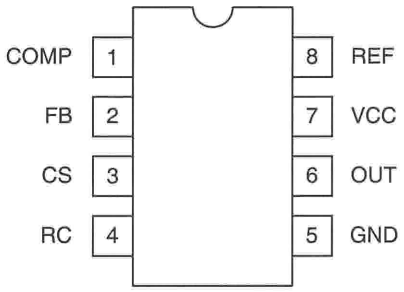


CONNECTION DIAGRAMS

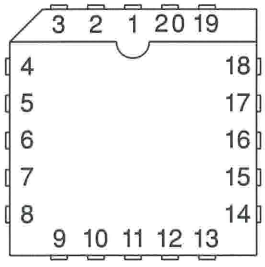
TSSOP-8 (Top View)
PW Package



DIL-8, SOIC-8 (Top View)
J or N, D Package



LCC-20
(TOP VIEW)
L Package



PACKAGE PIN FUNCTION	
FUNCTION	PIN
N/C	1
Comp	2
N/C	3-4
FB	5
N/C	6
CS	7
N/C	8-9
RC	10
N/C	11
PWR GND	12
GND	13
N/C	14
OUT	15
N/C	16
VCC	17
N/C	18-19
REF	20

ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for $-55°C \le T_A \le +125°C$ for UCC180x; $-40°C \le T_A \le +85°C$ for UCC280x; $0°C \le T_A \le +70°C$ for UCC380x; V_{CC}=10V (Note 3); RT=100k from REF to RC; CT=330pF from RC to GND; 0.1 F capacitor from V_{CC} to GND; 0.1 F capacitor from V_{REF} to GND. $T_A=T_J$.

PARAMETER	TEST CONDITIONS	UCC180X UCC280X			UCC380X			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
Reference Section								
Output Voltage	T_J=+25°C, I=0.2mA, UCCx800/1/2/4	4.925	5.00	5.075	4.925	5.00	5.075	V
	T_J=+25°C, I=0.2mA, UCCx803/5	3.94	4.00	4.06	3.94	4.00	4.06	
Load Regulation	0.2mA<I<5mA		10	30		10	25	mV
Line Regulation	T_J=+25°C, V_{CC}=10V to Clamp (I_{VCC}=25mA)			1.9			1.9	mV/V
	T_J=–55°C to +125°C, V_{CC}=10V to Clamp (I_{VCC}=25mA)			2.5			2.1	mV/V
Total Variation	UCCx800/1/2/4 (Note 7)	4.88	5.00	5.10	4.88	5.00	5.10	V
	UCCx803/5 (Note 7)	3.90	4.00	4.08	3.90	4.00	4.08	V
Output Noise Voltage	10Hz ≤ f ≤ 10kHz, T_J=+25°C (Note 9)		130			130		μV
Long Term Stability	T_A=+125°C, 1000 Hours (Note 9)		5			5		mV
Output Short Circuit		–5		–35	–5		–35	mA
Oscillator Section								
Oscillator Frequency	UCCx800/1/2/4 (Note 4)	40	46	52	40	46	52	kHz
	UCCx803/5 (Note 4)	26	31	36	26	31	36	kHz
Temperature Stability	(Note 9)		2.5			2.5		%
Amplitude peak-to-peak		2.25	2.40	2.55	2.25	2.40	2.55	V
Oscillator Peak Voltage			2.45			2.45		V
Error Amplifier Section								
Input Voltage	COMP=2.5V; UCCx800/1/2/4	2.44	2.50	2.56	2.44	2.50	2.56	V
	COMP=2.0V; UCCx803/5	1.95	2.0	2.05	1.95	2.0	2.05	
Input Bias Current		–1		1	–1		1	μA
Open Loop Voltage Gain		60	80		60	80		dB
COMP Sink Current	FB=2.7V, COMP=1.1V	0.3		3.5	0.4		2.5	mA
COMP Source Current	FB=1.8V, COMP=REF–1.2V	–0.2	–0.5	–0.8	–0.2	–0.5	–0.8	mA
Gain Bandwidth Product	(Note 9)		2			2		MHz
PWM Section								
Maximum Duty Cycle	UCCx800/2/3	97	99	100	97	99	100	%
	UCCx801/4/5	48	49	50	48	49	50	
Minimum Duty Cycle	COMP=0V			0			0	%
Current Sense Section								
Gain	(Note 5)	1.10	1.65	1.80	1.10	1.65	1.80	V/V
Maximum Input Signal	COMP=5V (Note 6)	0.9	1.0	1.1	0.9	1.0	1.1	V
Input Bias Current		–200		200	–200		200	nA
CS Blank Time		50	100	150	50	100	150	ns
Over-Current Threshold		1.42	1.55	1.68	1.42	1.55	1.68	V
COMP to CS Offset	CS=0V	0.45	0.90	1.35	0.45	0.90	1.35	V

ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for –55°C ≤ T_A ≤ +125°C for UCC180x; –40°C ≤ T_A ≤ +85°C for UCC280x; 0°C ≤ T_A ≤ +70°C for UCC380x; V_{CC}=10V (Note 3); RT=100k from REF to RC; CT=330pF from RC to GND; 0.1 F capacitor from V_{CC} to GND; 0.1 F capacitor from V_{REF} to GND. T_A=T_J.

PARAMETER	TEST CONDITIONS	UCC180X UCC280X			UCC380X			UNITS
Output Section								
OUT Low Level	I=20mA, all parts		0.1	0.4		0.1	0.4	V
	I=200mA, all parts		0.35	0.90		0.35	0.90	V
	I=50mA, VCC=5V, UCCx803/5		0.15	0.40		0.15	0.40	V
	I=20mA, VCC=0V, all parts		0.7	1.2		0.7	1.2	V
OUT High V_{SAT} (V_{CC}-OUT)	I=–20mA, all parts		0.15	0.40		0.15	0.40	V
	I=–200mA, all parts		1.0	1.9		1.0	1.9	V
	I=–50mA,VCC=5V, UCCx803/5		0.4	0.9		0.4	0.9	V
Rise Time	C_L=1nF		41	70		41	70	ns
Fall Time	C_L=1nF		44	75		44	75	ns
Undervoltage Lockout Section								
Start Threshold (Note 8)	UCCx800	6.6	7.2	7.8	6.6	7.2	7.8	V
	UCCx801	8.6	9.4	10.2	8.6	9.4	10.2	V
	UCCx802/4	11.5	12.5	13.5	11.5	12.5	13.5	V
	UCCx803/5	3.7	4.1	4.5	3.7	4.1	4.5	V
Stop Threshold (Note 8)	UCCx1800	6.3	6.9	7.5	6.3	6.9	7.5	V
	UCCx1801	6.8	7.4	8.0	6.8	7.4	8.0	V
	UCCx802/4	7.6	8.3	9.0	7.6	8.3	9.0	V
	UCCx803/5	3.2	3.6	4.0	3.2	3.6	4.0	V
Undervoltage Lockout Section (cont.)								
Start to Stop Hysteresis	UCCx800	0.12	0.3	0.48	0.12	0.3	0.48	V
	UCCx801	1.6	2	2.4	1.6	2	2.4	V
	UCCx802/4	3.5	4.2	5.1	3.5	4.2	5.1	V
	UCCx803/5	0.2	0.5	0.8	0.2	0.5	0.8	V
Soft Start Section								
COMP Rise Time	FB=1.8V, Rise from 0.5V to REF–1V		4	10		4	10	ms
Overall Section								
Start-up Current	V_{CC} < Start Threshold		0.1	0.2		0.1	0.2	mA
Operating Supply Current	FB=0V, CS=0V		0.5	1.0		0.5	1.0	mA
VCC Internal Zener Voltage	I_{CC}=10mA (Note 8), (Note 10)	12	13.5	15	12	13.5	15	V
VCC Internal Zener Voltage Minus Start Threshold Voltage	UCCx802/4 (Note 8)	0.5	1.0		0.5	1.0		V

Note 3: Adjust VCC above the start threshold before setting at 10V.

Note 4: Oscillator frequency for the UCCx800, UCCx802 and UCCx803 is the output frequency. Oscillator frequency for the UCCx801, UCCx804 and UCCx805 is twice the output frequency.

Note 5: Gain is defined by: $A = \frac{\Delta V_{COMP}}{\Delta V_{CS}}$ $0 \le V_{CS} \le 0.8V$.

Note 6: Parameter measured at trip point of latch with Pin 2 at 0V.

Note 7: Total Variation includes temperature stability and load regulation.

Note 8: Start Threshold, Stop Threshold and Zener Shunt Thresholds track one another.

Note 9: Guaranteed by design. Not 100% tested in production.

Note 10: The device is fully operating in clamp mode as the forcing current is higher than the normal operating supply current.

PIN DESCRIPTIONS

COMP: COMP is the output of the error amplifier and the input of the PWM comparator.

Unlike other devices, the error amplifier in the UCC3800 family is a true, low output-impedance, 2MHz operational amplifier. As such, the COMP terminal can both source and sink current. However, the error amplifier is internally current limited, so that you can command zero duty cycle by externally forcing COMP to GND.

The UCC3800 family features built-in full cycle Soft Start. Soft Start is implemented as a clamp on the maximum COMP voltage.

CS: CS is the input to the current sense comparators. The UCC3800 family has two different current sense comparators: the PWM comparator and an over-current comparator.

The UCC3800 family contains digital current sense filtering, which disconnects the CS terminal from the current sense comparator during the 100ns interval immediately following the rising edge of the OUT pin. This digital filtering, also called leading-edge blanking, means that in most applications, no analog filtering (RC filter) is required on CS. Compared to an external RC filter technique, the leading-edge blanking provides a smaller effective CS to OUT propagation delay. Note, however, that the minimum non-zero On-Time of the OUT signal is directly affected by the leading-edge-blanking and the CS to OUT propagation delay.

The over-current comparator is only intended for fault sensing, and exceeding the over-current threshold will cause a soft start cycle.

FB: FB is the inverting input of the error amplifier. For best stability, keep FB lead length as short as possible and FB stray capacitance as small as possible.

GND: GND is reference ground and power ground for all functions on this part.

OUT: OUT is the output of a high-current power driver capable of driving the gate of a power MOSFET with peak currents exceeding ± 750mA. OUT is actively held low when V_{CC} is below the UVLO threshold.

The high-current power driver consists of FET output devices, which can switch all of the way to GND and all of the way to V_{CC}. The output stage also provides a very low impedance to overshoot and undershoot. This means that in many cases, external schottky clamp diodes are not required.

RC: RC is the oscillator timing pin. For fixed frequency operation, set timing capacitor charging current by connecting a resistor from REF to RC. Set frequency by connecting a timing capacitor from RC to GND. For best performance, keep the timing capacitor lead to GND as short and direct as possible. If possible, use separate ground traces for the timing capacitor and all other functions.

The frequency of oscillation can be estimated with the following equations:

$$\text{UCCx800/1/2/4:} \quad F = \frac{1.5}{R \bullet C}$$

$$\text{UCCx803, UCCx805:} \quad F = \frac{1.0}{R \bullet C}$$

where frequency is in Hz, resistance is in ohms, and capacitance is in farads. The recommended range of timing resistors is between 10k and 200k and timing capacitor is 100pF to 1000pF. Never use a timing resistor less than 10k.

To prevent noise problems, bypass VCC to GND with a ceramic capacitor as close to the VCC pin as possible. An electrolytic capacitor may also be used in addition to the ceramic capacitor.

REF: REF is the voltage reference for the error amplifier and also for many other functions on the IC. REF is also used as the logic power supply for high speed switching logic on the IC.

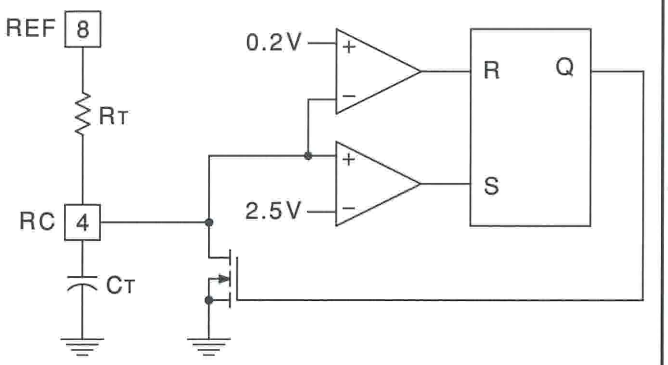
When V_{CC} is greater than 1V and less than the UVLO threshold, REF is pulled to ground through a 5k ohm resistor. This means that REF can be used as a logic output indicating power system status. It is important for reference stability that REF is bypassed to GND with a ceramic capacitor as close to the pin as possible. An electrolytic capacitor may also be used in addition to the ceramic capacitor. A minimum of 0.1µF ceramic is required. Additional REF bypassing is required for external loads greater than 2.5mA on the reference.

To prevent noise problems with high speed switching transients, bypass REF to ground with a ceramic capacitor very close to the IC package.

VCC: V_{CC} is the power input connection for this device. In normal operation V_{CC} is powered through a current limiting resistor. Although quiescent V_{CC} current is very low, total supply current will be higher, depending on OUT current. Total V_{CC} current is the sum of quiescent V_{CC} current and the average OUT current. Knowing the operating frequency and the MOSFET gate charge (Qg), average OUT current can be calculated from:

$$I_{OUT} = Q_g \times F.$$

There should be a minimum of 1.0µF in parallel with a 0.1µF ceramic capacitor from V_{CC} to ground located close to the device



The UCC3800/1/2/3/4/5 oscillator generates a sawtooth waveform on RC. The rise time is set by the time constant of RT and CT. The fall time is set by CT and an internal transistor on-resistance of approximately 125 . During the fall time, the output is off and the maximum duty cycle is reduced below 50% or 100% depending on the part number. Larger timing capacitors increase the discharge time and reduce the maximum duty cycle and frequency.

Figure 1. Oscillator.

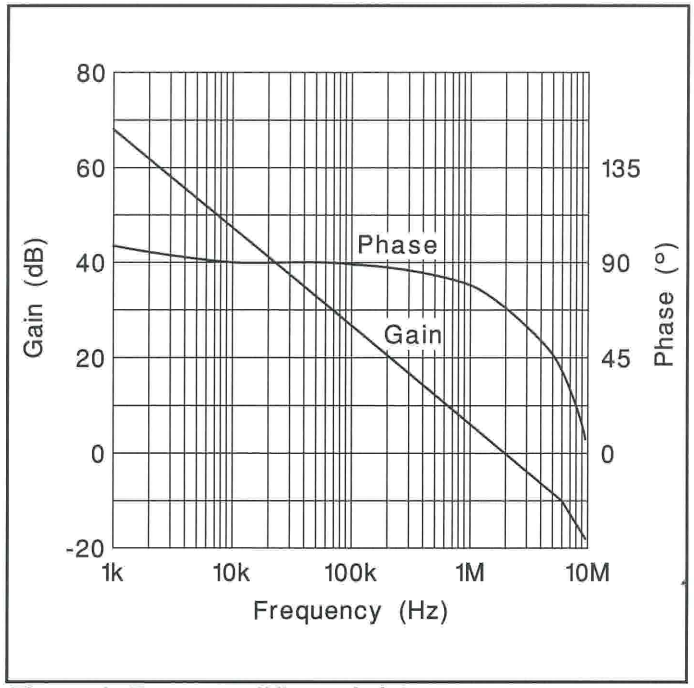


Figure 2. Error amplifier gain/phase response.

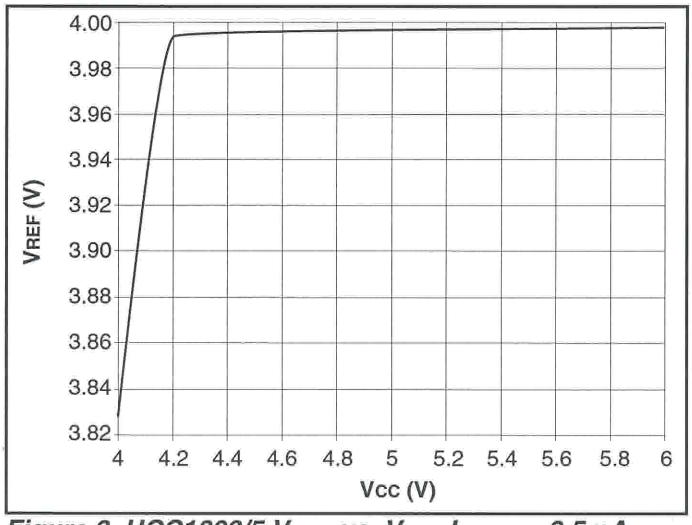


Figure 3. UCC1803/5 V_{REF} vs. V_{CC}; I_{LOAD} = 0.5mA.

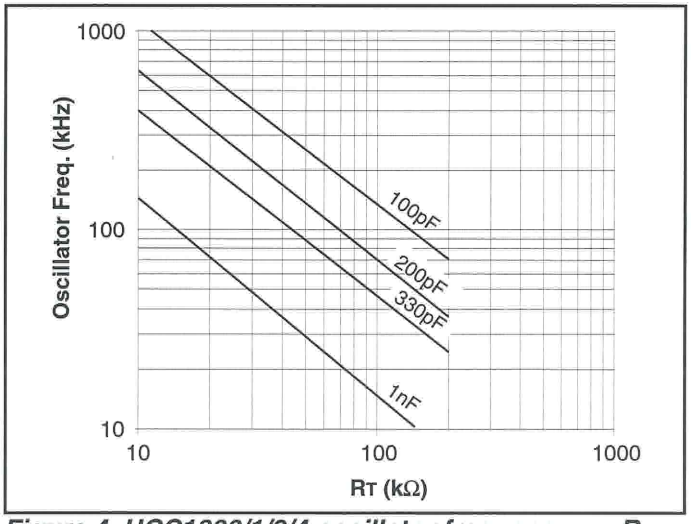


Figure 4. UCC1800/1/2/4 oscillator frequency vs. R_T and C_T.

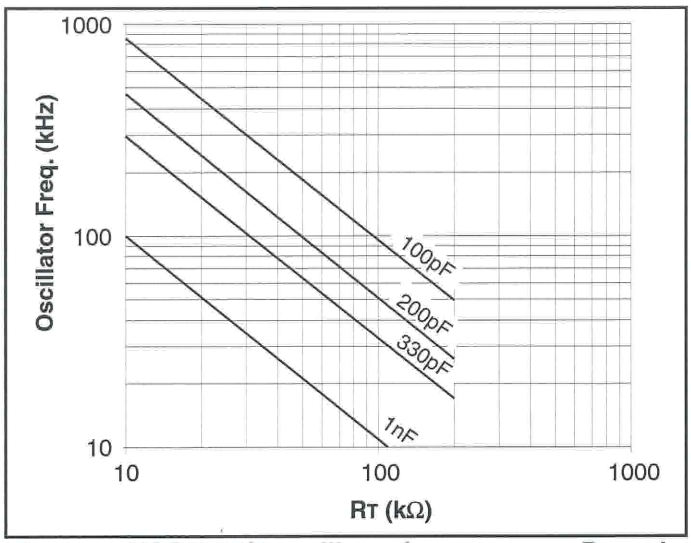


Figure 5. UCC1803/5 oscillator frequency vs. R_T and C_T.

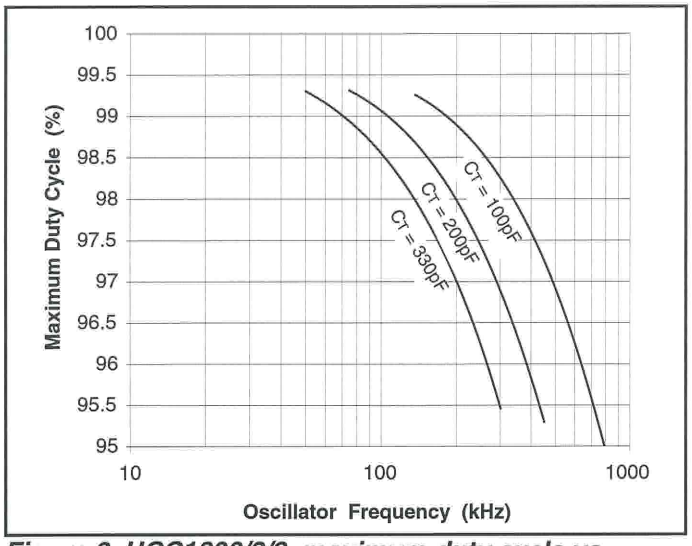


Figure 6. UCC1800/2/3 maximum duty cycle vs. oscillator frequency.

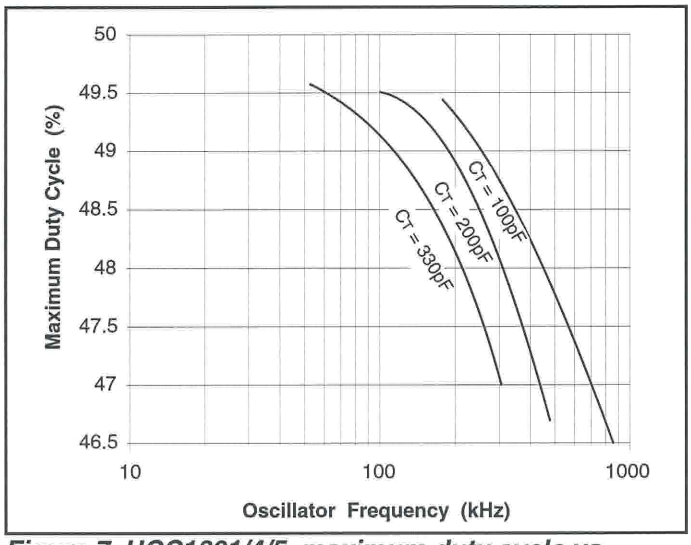


Figure 7. UCC1801/4/5 maximum duty cycle vs. oscillator frequency.

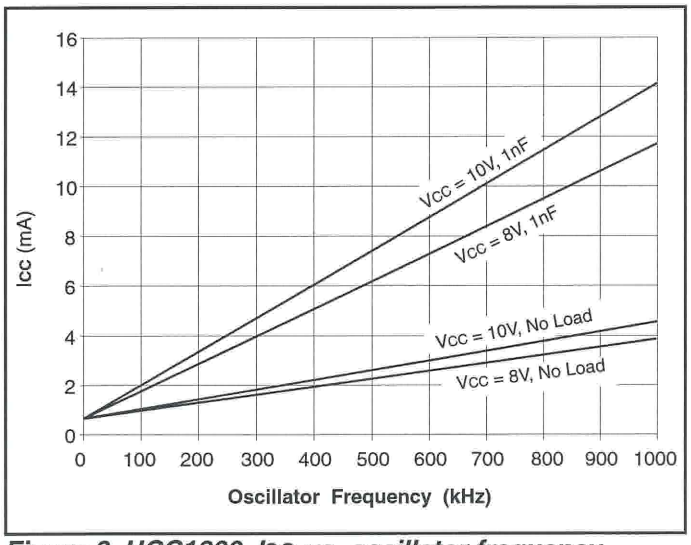


Figure 8. UCC1800 I_{CC} vs. oscillator frequency.

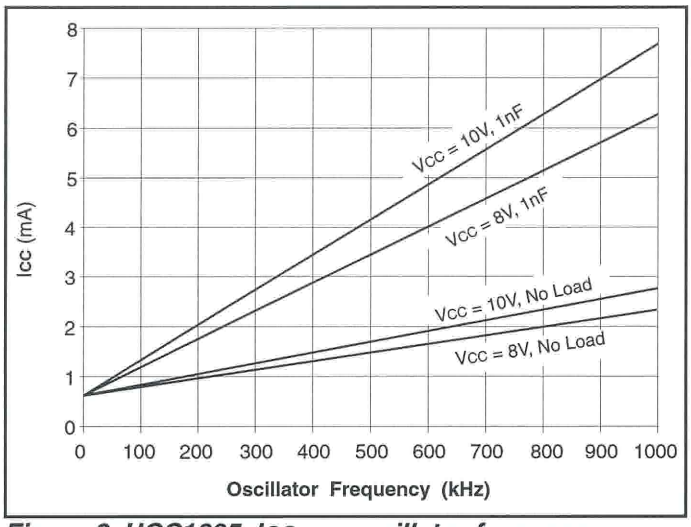


Figure 8. UCC1805 I_{CC} vs. oscillator frequency.

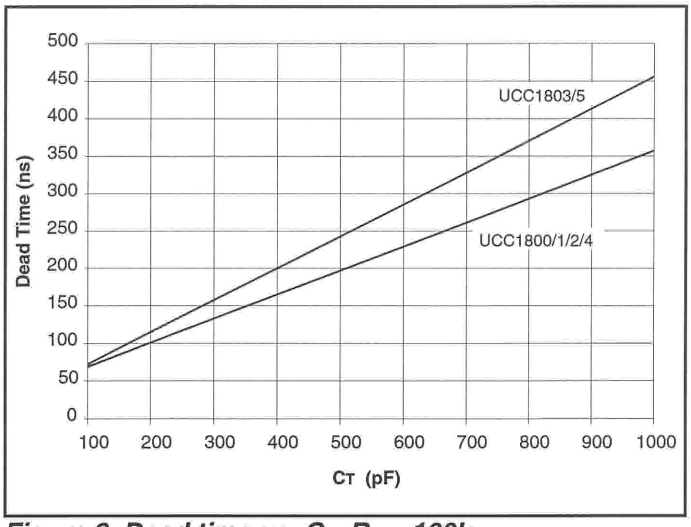


Figure 9. Dead time vs. C_T, R_T = 100k.

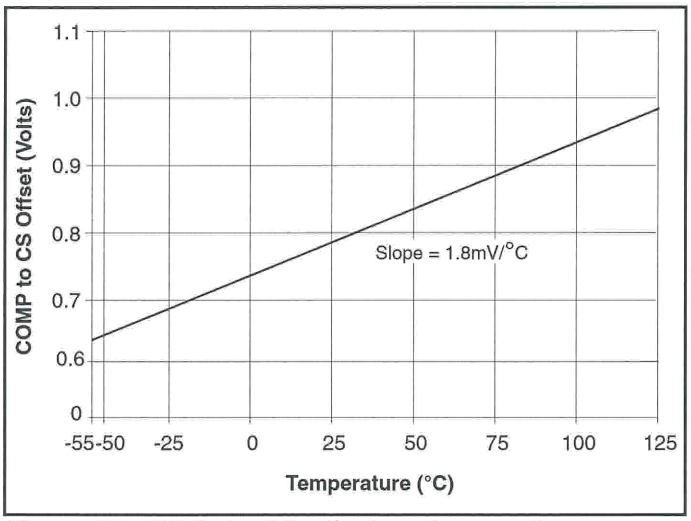


Figure 10. COMP to CS offset vs. temperature, CS = 0V.

REVISION HISTORY

8/2010 Revision A to Revision B

Updated Abs Max Table to read:

Analog Inputs (FB, CS, RC, COMP).....–0.3V to the lesser of 6.3V or VCC + 0.3V

From: Analog Inputs (FB, CS).....–0.3V to 6.3V

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9451301MPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9451301MPA UCC1801	Samples
5962-9451302MPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9451302MPA UCC1802	Samples
5962-9451303MPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9451303MPA UCC1803	Samples
5962-9451304MPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9451304MPA UCC1804	Samples
5962-9451305MPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9451305MPA UCC1805	Samples
UCC1800J	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	UCC1800J	Samples
UCC1800J883B	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	UCC1800J/ 883B	Samples
UCC1800L883B	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	UCC1800L/ 883B	Samples
UCC1801J	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	UCC1801J	Samples
UCC1801J883B	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9451301MPA UCC1801	Samples
UCC1802J	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	UCC1802J	Samples
UCC1802J883B	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9451302MPA UCC1802	Samples
UCC1803J	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	UCC1803J	Samples
UCC1803J883B	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9451303MPA UCC1803	Samples
UCC1804J	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	UCC1804J	Samples
UCC1804J883B	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9451304MPA UCC1804	Samples
UCC1805J	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	UCC1805J	Samples
UCC1805J883B	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9451305MPA UCC1805	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UCC2800D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2800	Samples
UCC2800DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2800	Samples
UCC2800DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2800	Samples
UCC2800DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2800	Samples
UCC2800N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UCC2800N	Samples
UCC2800NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UCC2800N	Samples
UCC2800PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2800	Samples
UCC2800PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2800	Samples
UCC2801D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2801	Samples
UCC2801DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2801	Samples
UCC2801DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2801	Samples
UCC2801DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2801	Samples
UCC2801N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UCC2801N	Samples
UCC2801NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UCC2801N	Samples
UCC2801PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2801	Samples
UCC2801PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2801	Samples
UCC2802-W	ACTIVE	WAFERSALE	YS	0		TBD	Call TI	Call TI			Samples
UCC2802D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2802	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UCC2802DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2802	Samples
UCC2802DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2802	Samples
UCC2802DTRG4	ACTIVE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 85		Samples
UCC2802J	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-40 to 85	UCC2802J	Samples
UCC2802N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UCC2802N	Samples
UCC2802NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UCC2802N	Samples
UCC2802PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2802	Samples
UCC2803D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2803	Samples
UCC2803DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2803	Samples
UCC2803DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2803	Samples
UCC2803DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2803	Samples
UCC2803N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UCC2803N	Samples
UCC2803NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UCC2803N	Samples
UCC2803PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2803	Samples
UCC2803PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2803	Samples
UCC2803PWTR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2803	Samples
UCC2803PWTRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2803	Samples
UCC2804D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2804	Samples
UCC2804D/70021	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI			

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UCC2804DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2804	Samples
UCC2804DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2804	Samples
UCC2804DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2804	Samples
UCC2804N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UCC2804N	Samples
UCC2804NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UCC2804N	Samples
UCC2804PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2804	Samples
UCC2804PWTR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2804	Samples
UCC2805-W	ACTIVE	WAFERSALE	YS	0		TBD	Call TI	Call TI			Samples
UCC2805D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2805	Samples
UCC2805DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2805	Samples
UCC2805DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2805	Samples
UCC2805DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	UCC2805	Samples
UCC2805N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UCC2805N	Samples
UCC2805PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2805	Samples
UCC2805PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2805	Samples
UCC2805PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2805	Samples
UCC3800D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3800	Samples
UCC3800DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3800	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UCC3800DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3800	Samples
UCC3800N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3800N	Samples
UCC3800NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3800N	Samples
UCC3800PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	3800	Samples
UCC3801D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3801	Samples
UCC3801DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3801	Samples
UCC3801DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3801	Samples
UCC3801DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3801	Samples
UCC3801N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3801N	Samples
UCC3801NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3801N	Samples
UCC3801PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	3801	Samples
UCC3801PWTR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	3801	Samples
UCC3802-W	ACTIVE	WAFERSALE	YS	0		TBD	Call TI	Call TI			Samples
UCC3802D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3802	Samples
UCC3802DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3802	Samples
UCC3802DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3802	Samples
UCC3802DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3802	Samples
UCC3802N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3802N	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UCC3802NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3802N	Samples
UCC3802PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	3802	Samples
UCC3803D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3803	Samples
UCC3803DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3803	Samples
UCC3803DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3803	Samples
UCC3803DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3803	Samples
UCC3803N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3803N	Samples
UCC3803NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3803N	Samples
UCC3803PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	3803	Samples
UCC3803PWTR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	3803	Samples
UCC3803PWTRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	3803	Samples
UCC3804D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3804	Samples
UCC3804DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3804	Samples
UCC3804DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3804	Samples
UCC3804DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3804	Samples
UCC3804N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3804N	Samples
UCC3804NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3804N	Samples
UCC3804PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	3804	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UCC3804PWTR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	3804	Samples
UCC3805D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3805	Samples
UCC3805DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3805	Samples
UCC3805DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3805	Samples
UCC3805DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UCC3805	Samples
UCC3805N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3805N	Samples
UCC3805NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UCC3805N	Samples
UCC3805PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	3805	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF UCC1800, UCC1801, UCC1802, UCC1803, UCC1804, UCC1805, UCC1805-SP, UCC2800, UCC2801, UCC2802, UCC2802M, UCC2803, UCC2803M, UCC2804, UCC2805, UCC3800, UCC3801, UCC3802, UCC3803, UCC3804, UCC3805 :

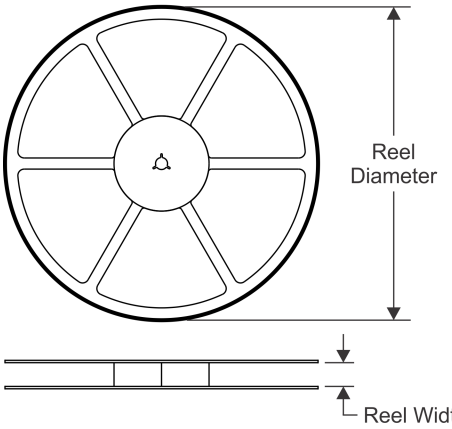
- Catalog: UCC3800, UCC3801, UCC3802, UCC3803, UCC3804, UCC3805, UCC1805, UCC2802, UCC2803
- Automotive: UCC2800-Q1, UCC2801-Q1, UCC2802-Q1, UCC2802-Q1, UCC2803-Q1, UCC2803-Q1, UCC2804-Q1, UCC2805-Q1
- Enhanced Product: UCC2800-EP, UCC2801-EP, UCC2802-EP, UCC2802-EP, UCC2803-EP, UCC2803-EP, UCC2804-EP, UCC2805-EP
- Military: UCC2802M, UCC2803M, UCC1800, UCC1801, UCC1802, UCC1803, UCC1804, UCC1805
- Space: UCC1805-SP

NOTE: Qualified Version Definitions:

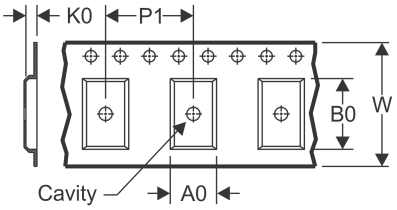
- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

REEL DIMENSIONS

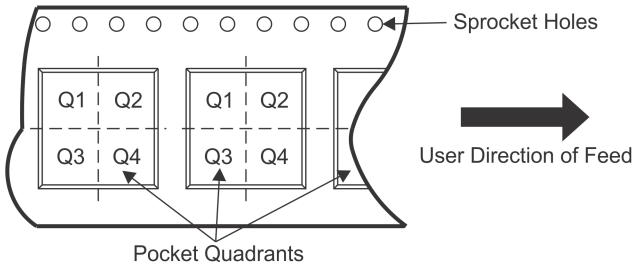


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

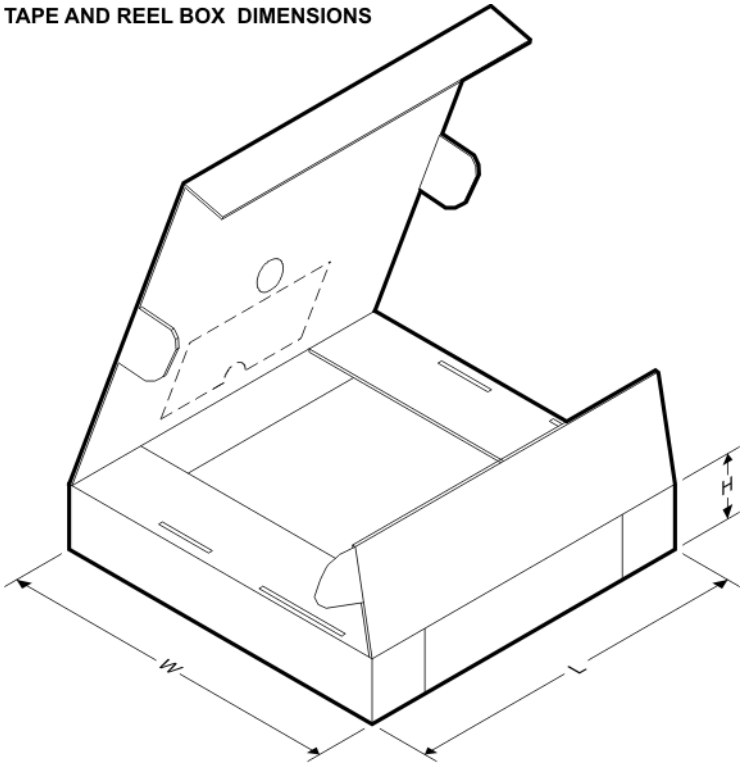
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UCC2800DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC2801DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC2802DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC2803DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC2803PWTR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
UCC2804DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC2804PWTR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
UCC2805DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC2805PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
UCC3800DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC3801DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC3801PWTR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
UCC3802DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC3803DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC3803PWTR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
UCC3804DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC3804PWTR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
UCC3805DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

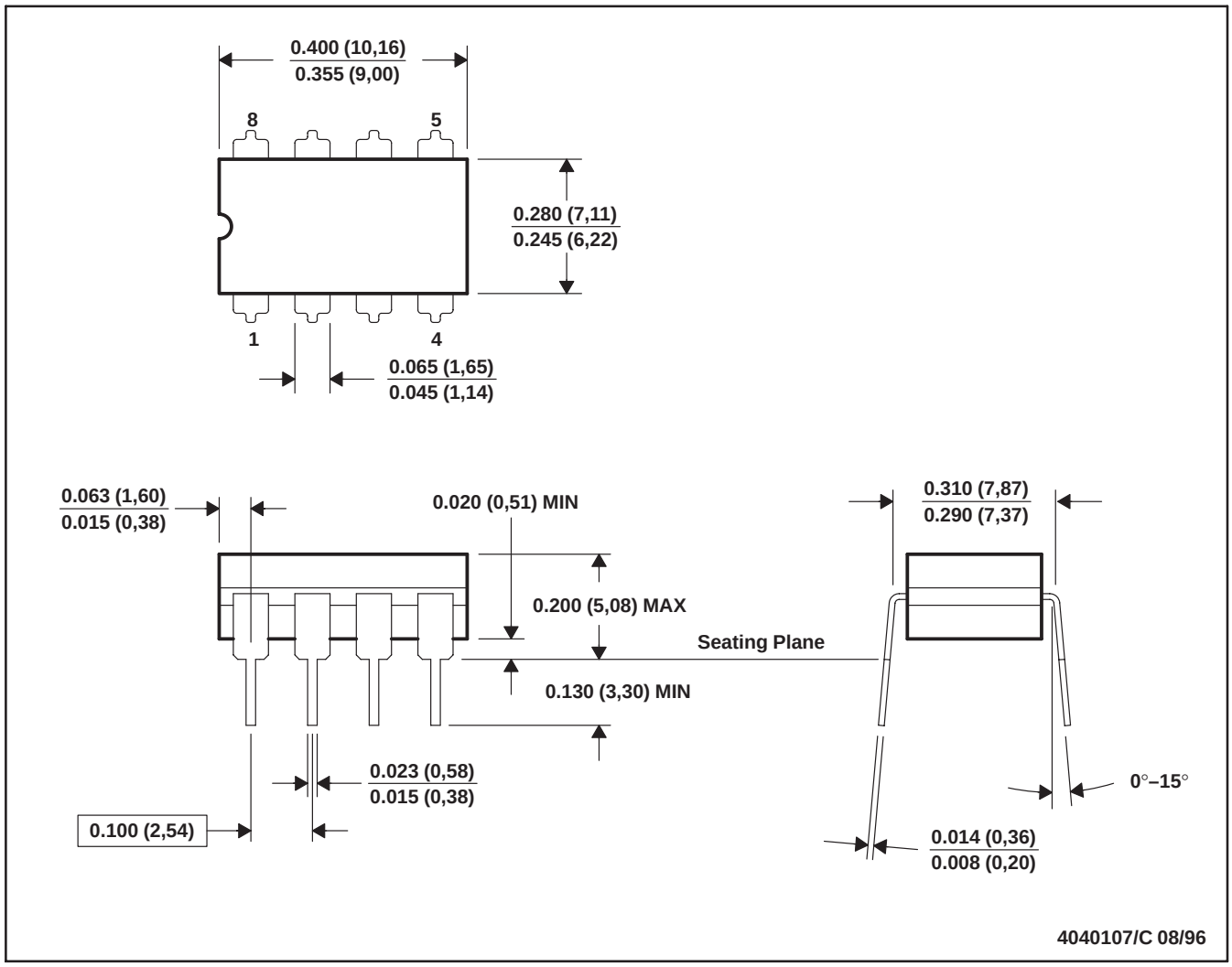


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UCC2800DTR	SOIC	D	8	2500	340.5	338.1	20.6
UCC2801DTR	SOIC	D	8	2500	340.5	338.1	20.6
UCC2802DTR	SOIC	D	8	2500	340.5	338.1	20.6
UCC2803DTR	SOIC	D	8	2500	340.5	338.1	20.6
UCC2803PWTR	TSSOP	PW	8	2000	367.0	367.0	35.0
UCC2804DTR	SOIC	D	8	2500	340.5	338.1	20.6
UCC2804PWTR	TSSOP	PW	8	2000	367.0	367.0	35.0
UCC2805DTR	SOIC	D	8	2500	340.5	338.1	20.6
UCC2805PWR	TSSOP	PW	8	2000	367.0	367.0	35.0
UCC3800DTR	SOIC	D	8	2500	340.5	338.1	20.6
UCC3801DTR	SOIC	D	8	2500	340.5	338.1	20.6
UCC3801PWTR	TSSOP	PW	8	2000	367.0	367.0	35.0
UCC3802DTR	SOIC	D	8	2500	340.5	338.1	20.6
UCC3803DTR	SOIC	D	8	2500	340.5	338.1	20.6
UCC3803PWTR	TSSOP	PW	8	2000	367.0	367.0	35.0
UCC3804DTR	SOIC	D	8	2500	340.5	338.1	20.6
UCC3804PWTR	TSSOP	PW	8	2000	367.0	367.0	35.0
UCC3805DTR	SOIC	D	8	2500	340.5	338.1	20.6

MCER001A – JANUARY 1995 – REVISED JANUARY 1997

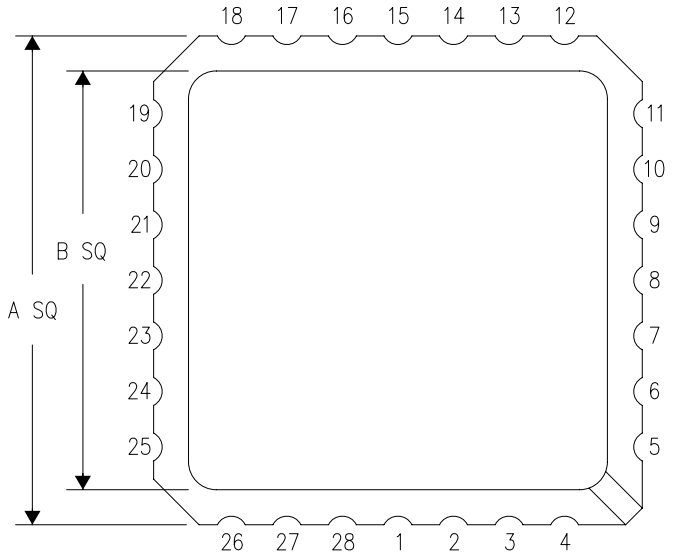
JG (R-GDIP-T8) **CERAMIC DUAL-IN-LINE**



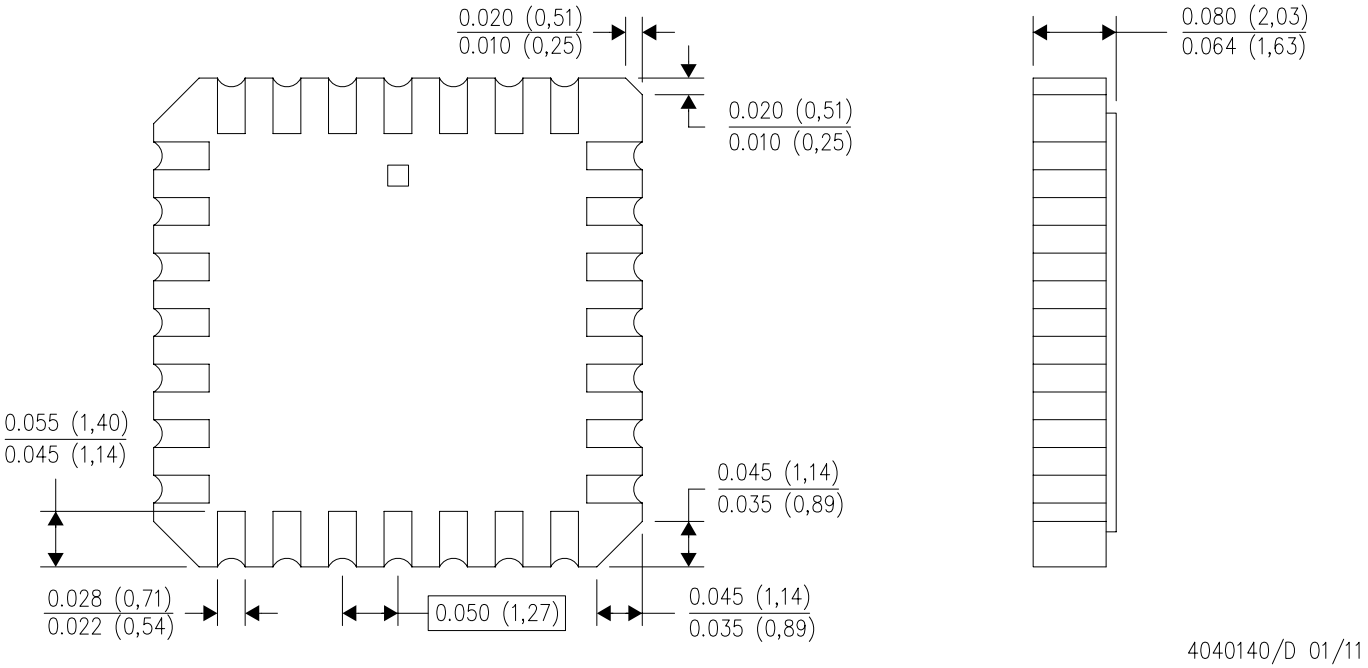
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification.
E. Falls within MIL STD 1835 GDIP1-T8

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



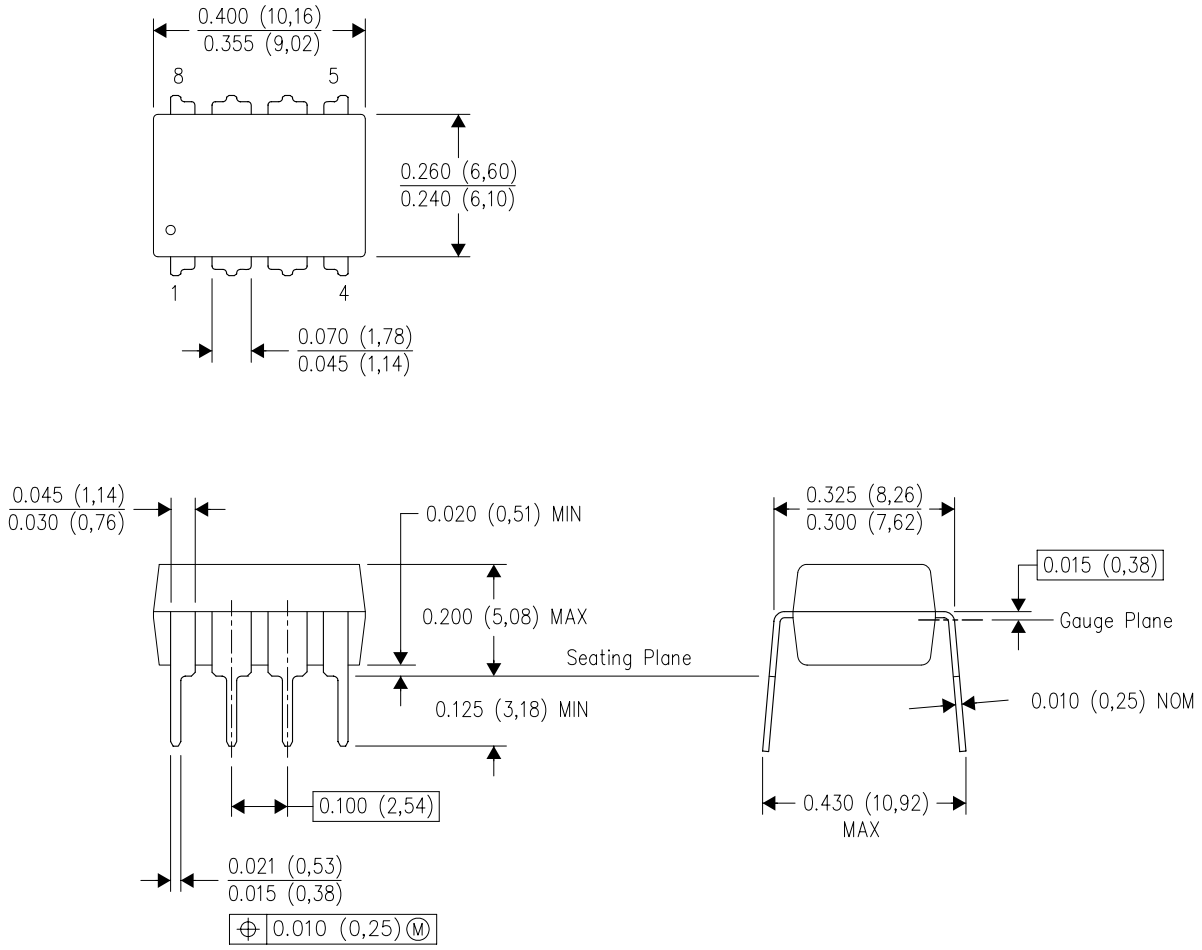
NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



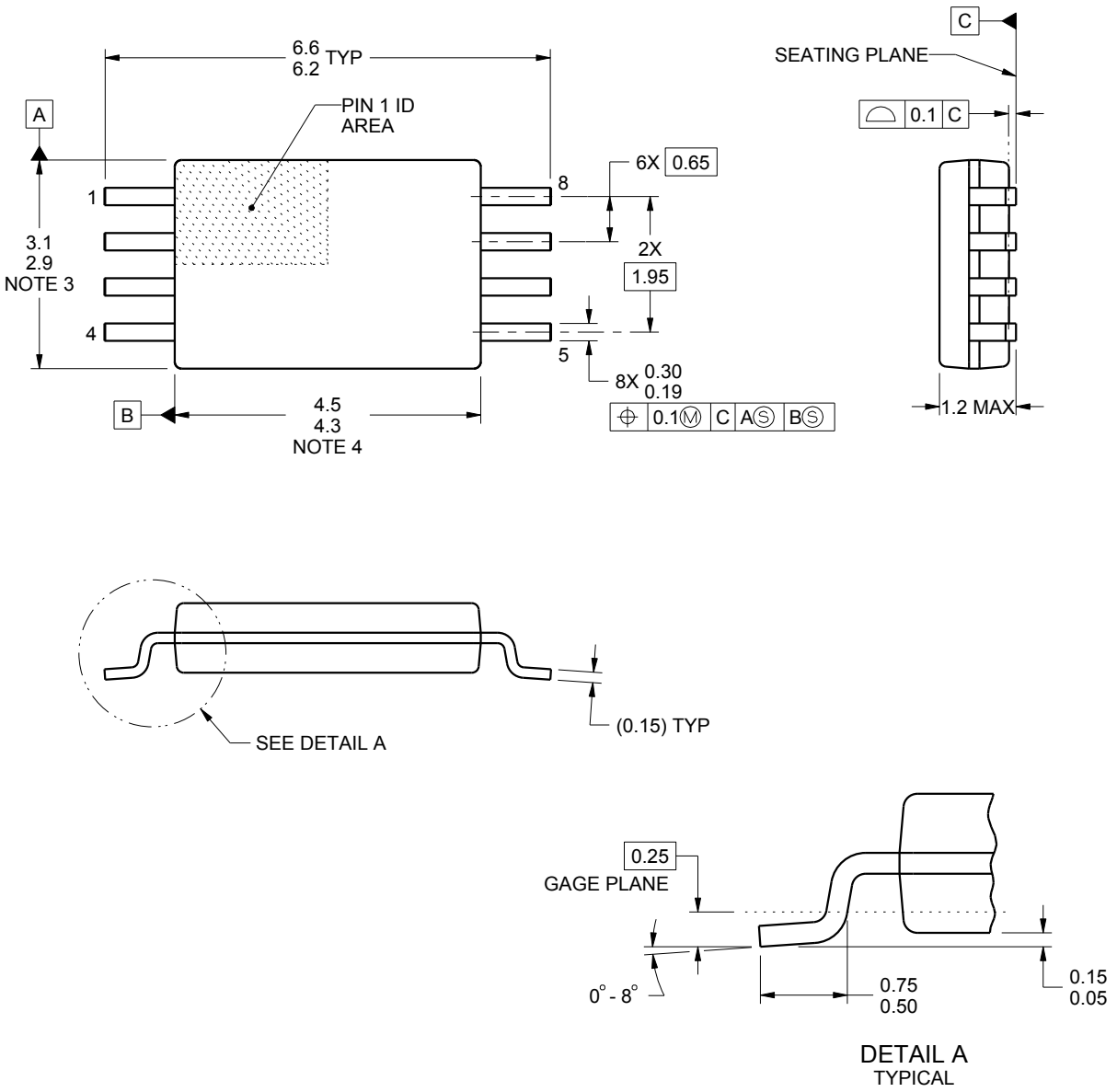
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

PACKAGE OUTLINE

PW0008A

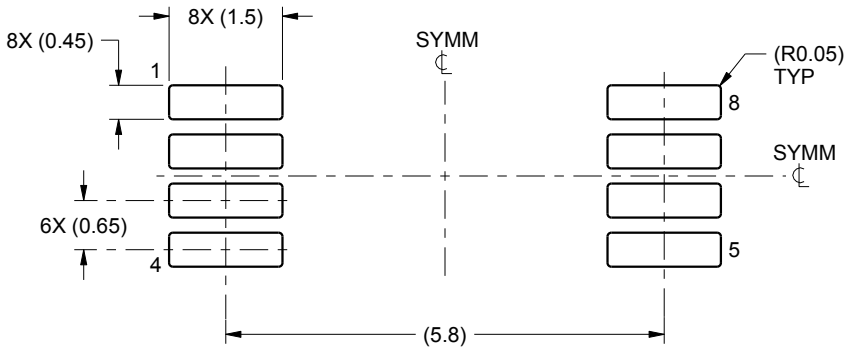
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

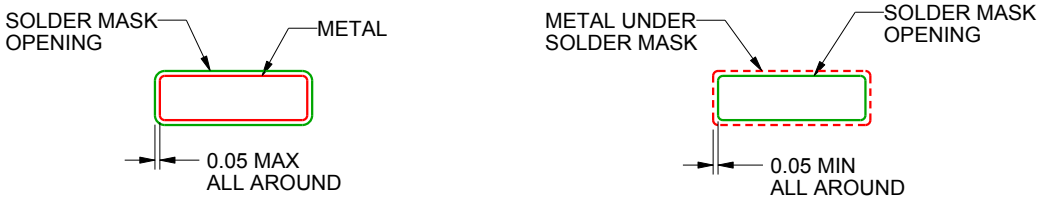


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.



LAND PATTERN EXAMPLE
SCALE:10X

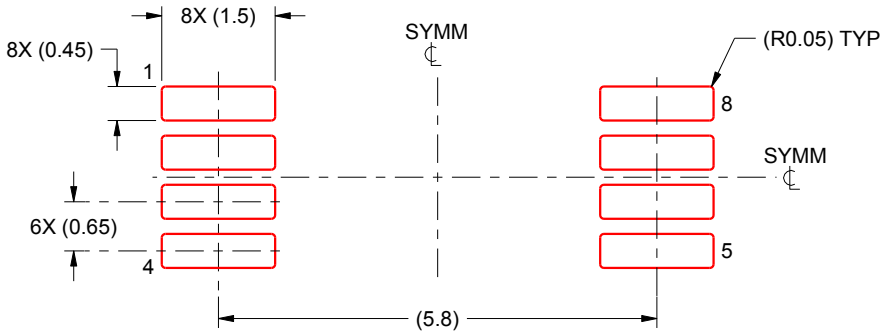


SOLDER MASK DETAILS
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



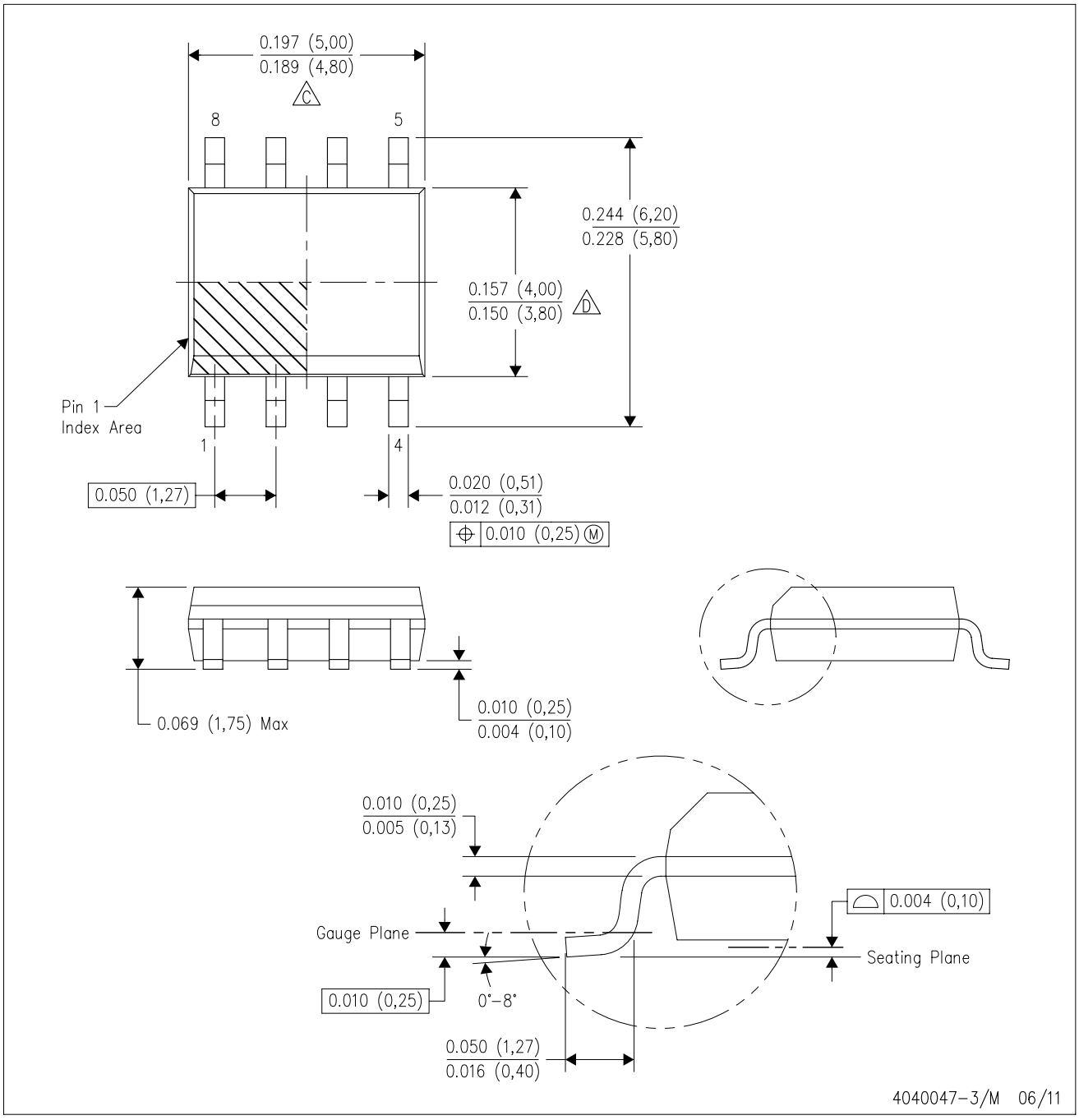
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221848/A 02/2015

NOTES: (continued)

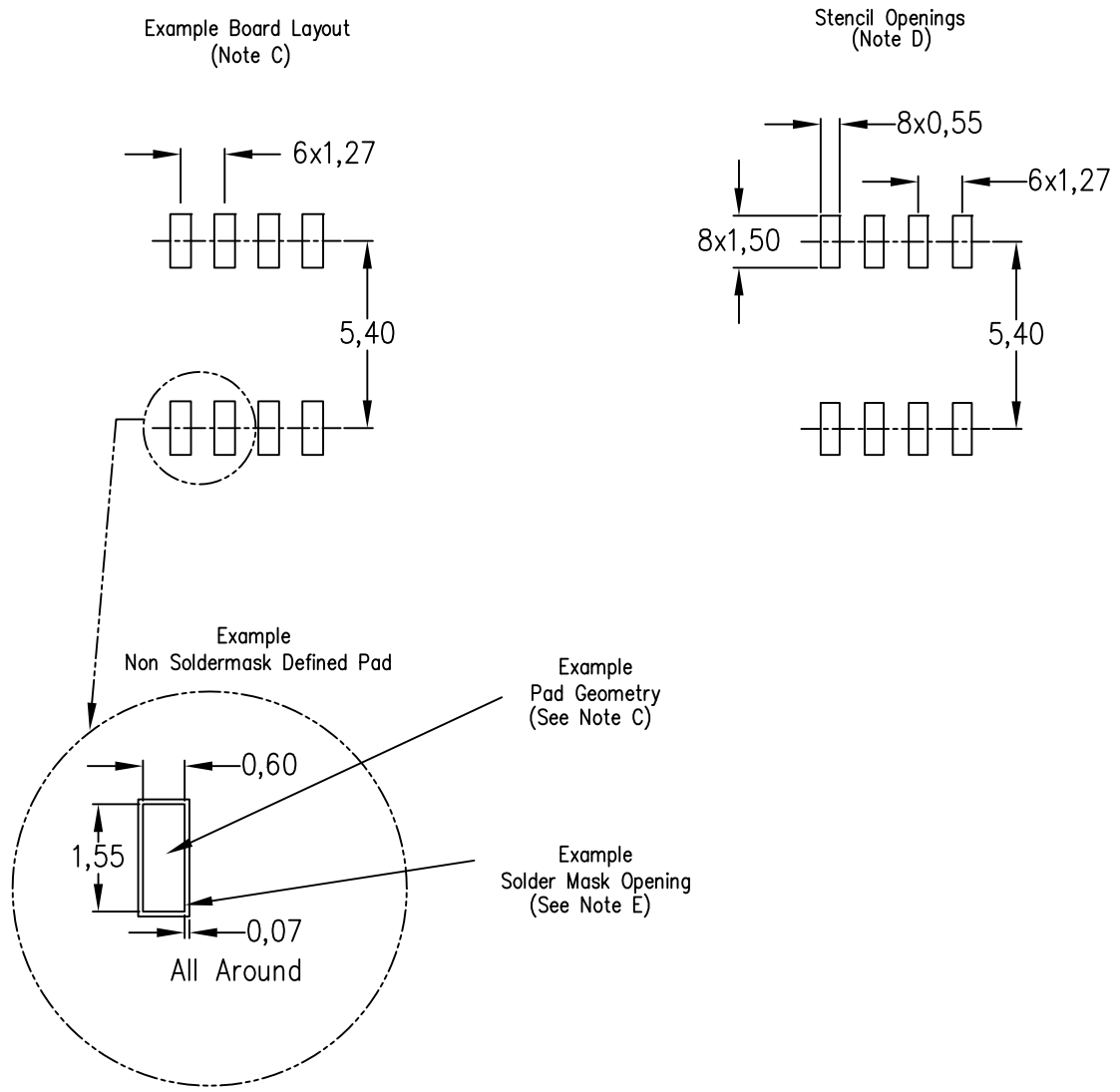
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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